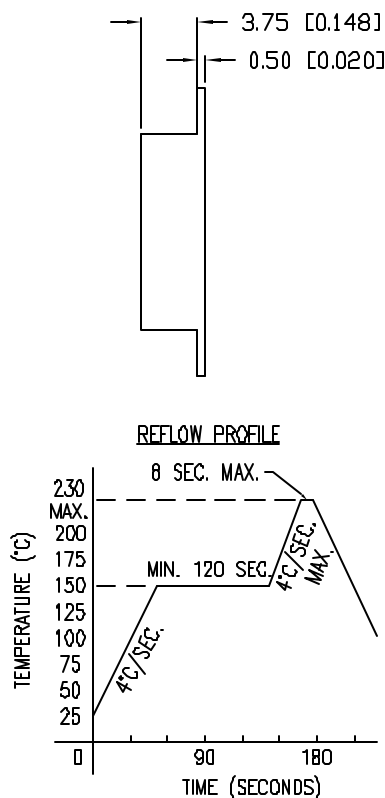


PART NUMBER
LDS-SMCAN4006RI

Figure 6 shows a plan view of the second embodiment of the semiconductor device. The device has a rectangular shape with a central diamond-shaped region. Key dimensions and features include:

- Top Edge Dimensions:** Total width is 9.30 [0.366]. A segment at the top right is 2.60 [0.102] (2 PLS.).
- Left Edge Dimensions:** Total height is 19.00 [0.748]. Segments from top are 14.20 [0.559] and 13.00 [0.512].
- Internal Features:** A central diamond-shaped region is surrounded by a grid of squares. There are four small circles (vias) arranged in two rows of two.
- Bottom Edge Dimensions:** Total width is 9.30 [0.366]. A segment at the bottom right is 2.60 [0.102] (2 PLS.).
- Right Edge Dimensions:** Total height is 19.00 [0.748]. A segment at the bottom right is 2.60 [0.102] (2 PLS.).
- Other Dimensions:** 1.20 [0.047] (6 PLS.) is indicated for several segments along the edges.
- Curvature:** R0.32 [R0.013] is indicated for the rounded corners.



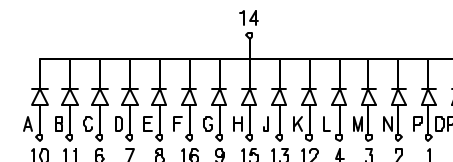
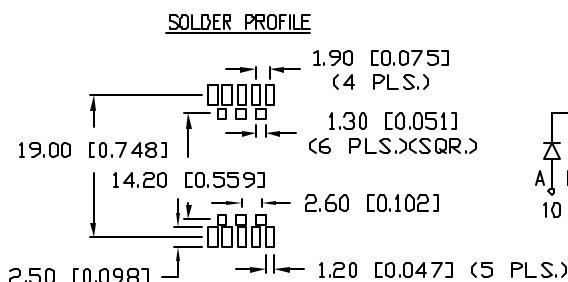
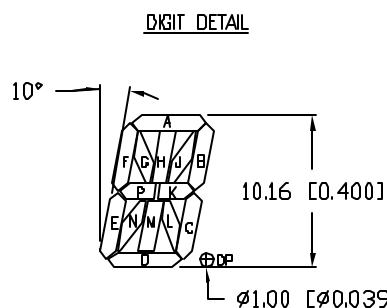
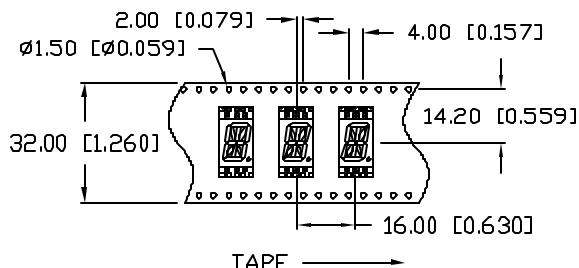
ELECTRO—OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$			$I_f=10\text{mA}$		
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		650 (RED)		nm	
FORWARD VOLTAGE *		1.85	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		16200		μcd	$I_f=10\text{mA}$
EMITTED COLOR:	RED				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	155	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	- 1.2	mW/°C
OPERATING, STORAGE TEMP.	- 40 TO + 85	°C
SOLDERING TEMP.	+230	°C

* $t < 10\mu s$

1. 800 PCS/REEL

POLARITY DIAGRAM



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.=+DECIMAL PRECISION -0.00 MAX.=+0.00 -DECIMAL PRECISION

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.40" SMT ALPHA/NUMERIC DISPLAY COMMON
CATHODE, 660nm SUPER RED, GRY/WHITE.

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RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT
SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE.
PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

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SCALE: N/A